

14th Fraunhofer Symposium in Sendai
November 21, 2023 | Sakura Hall

Innovation of Semiconductor Research and Creation – Technologies and Components for Heterogeneous System Integration

Registration

I will attend in:

Symposium Lunch Reception

Participate as exhibitor

Please fill in the form and send it as e-mail to
fraunhofer-symposium@enas.fraunhofer.de |
fax: +81 22 795 6259

The Fraunhofer Symposium is held in cooperation with Tohoku
University and takes place in the Sakura Hall.

www.tohoku.ac.jp/en/about/facilities/conferences_events/214_sakura_hall.html

Contact details

Mr. Mrs.

Name, Surname

Company

Address (Street, ZIP, City, Country)

E-Mail

Phone

It is organized by Fraunhofer ENAS (Germany) in cooperation
with the Fraunhofer Office Japan in Tokyo and the Micro
System Integration Center of Tohoku University.

Each participant has the opportunity to reserve an exhibition
stand free of charge.

More information and the online registration form:
<https://www.enas.fraunhofer.de/fraunhofer-symposium>

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Program

10:00 – 10:10 am	Welcome and Opening Hideya Miki, Fraunhofer Japan Prof. Aoki, Tohoku University	2:00 – 2:30 pm	Break Exhibition
10:10 – 11:50 am	Keynote Session Transfer of R&D to the Industry – Test and Reliability Center Prof. Harald Kuhn, Fraunhofer ENAS Open Collaboration for R&D and Human Resource Development Prof. Kentaro Totsu, Tohoku University Flexible Optical Waveguides and Microoptics for Medical Implants in the Context of Optogenetics Prof. Ulrich T. Schwarz, Chemnitz University of Technology Nanoengineered Micro/Nanosystems Prof. Takahito Ono, Tohoku University	2:30 – 3:30 pm	Session “Integration” Heterogeneous Integration Based on Room-Temperature Bonding for MEMS and Sensors Prof. Eiji Higurashi, Tohoku University Room Temperature Oxide-Free Direct Bonding for Next Level Heterogenous Integration Tobias Wernicke, EV Group Heterogeneous System Integration Approaches by a Silicon Foundry Stefan Ernst, X-FAB MEMS Foundry GmbH
11:50 am – 1:00 pm	Lunch Break Exhibition	3:30 – 4:00 pm	Break Exhibition
1:00 – 2:00 pm	Session “Fabrication” Innovation of Microsystems based on Wafer Bonding Technology Prof. Shuji Tanaka, Tohoku University Smart Sensor Systems for High-Temperature Application by Integration with a SiC CMOS Technology Michael Jank, Fraunhofer IISB Innovations in Wafer Bonding for the Fabrication of Smart Systems Dr. Maik Wiemer, Fraunhofer ENAS	4:00 – 5:00 pm	Session “Test” NanoTerasu; Next Generation SR Facility Building a New Range of Innovation Ecosystem Prof. Masaki Takata, Tohoku University N.N. Photonic Integrated Circuits for Testing Shunsuke Abe, Advantest Corporation
		5:00 – 7:00 pm	Dinner Reception